

PTO/SB/064 (10-01)
Approved for use through 10/31/2002. OMB 85-10031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO
**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Use as many sheets as necessary)

FEB 20 2004
PATENT & TRADEMARK OFFICE

Complete if Known

Applicant Number	09/854539
Filing Date	May 14, 2001
First Named Inventor	Intel Corporation, .
Group Art Unit	2814
Examiner Name	Peralta, Ginette

Sheet 1 of 2
Attorney Docket No: 884.415US1

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
JP	US-2001/0013654-A1	08/16/2001	Kalidas, N., et al.	257	738	12/22/1999
JP	US-2002/0008314-A1	01/24/2002	Takeuchi, Y.	257	697	04/13/2000
JP	US-5,105,257	04/14/1992	Michii, K.	357	70	02/04/1991
JP	US-5,608,262	03/04/1997	Degani, Y., et al.	257	723	02/24/1995
JP	US-5,701,032	12/23/1997	Fischer, P. J., et al.	257	692	11/02/1995
JP	US-5,864,470	01/26/1999	Shim, I. K., et al.	361	777	06/25/1997
JP	US-6,084,297	07/04/2000	Brooks, J. M., et al.	257	698	09/03/1998
JP	US-6,084,777	07/04/2000	Kalidas, N., et al.	361	707	04/23/1998
JP	US-6,130,478	10/10/2000	Dumoulin, A., et al.	257	728	04/18/1998
JP	US-6,222,246	04/24/2001	Mak, T. M., et al.	257	532	01/08/1999
JP	US-6,239,482	05/29/2001	Fillion, Raymond A., et al.	257	678	06/21/1999
JP	US-6,388,333	05/14/2002	Taniguchi, F., et al.	257	777	06/27/2000
JP	US-6,590,291	07/08/2003	Akagawa, M.	257	774	01/25/2001

FOREIGN PATENT DOCUMENTS						
Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
JP	EP-0149317	07/24/1985	Heeks, J. S., et al.	H05K	3/28	
JP	EP-0361825	04/04/1990	Misawa, H.	H01L	23/522	
JP	EP-0431205	06/12/1991	Schroeder, J. A.	H01L	23/498	
JP	JP-10-125721	05/15/1998	Chikako, H.	H01L	21/60	
JP	JP-11-204688	07/30/1999	Kenji, A.	H01L	23/12	
JP	JP-2000-243870	09/08/2000	Akira, K.	H01L	23/12	
JP	JP-2000-307005	11/02/2000	Yasushi, T.	H01L	21/82	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
JP		CHEN, CHANG-LEE, et al., "Bond Wireless Multichip Packaging Technology for High-Speed Circuits", IEEE Transactions on Components, Hybrids, and Manufacturing Technology, 15, NY, US, (1992), 451-456	
JP		DAUM, W., et al., "Overlay High-Density Interconnect: A Chips-First Multichip Module Technology", IEEE Computer Society, 26, Long Beach, CA, US, (1993), 23-29	
JP		GDULA, MICHAEL, et al., "An Overlay Interconnect Technology for 1GHz. and Above MCMs", Proceedings of the Multi Chip Module Conference (MCMC), Santa Cruz, US, (1992), 171-174	

EXAMINER

Ginette Peralta

DATE CONSIDERED

4/16/04

Substitute Disclosure Statement Form (PTO-1449)
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached